



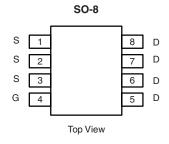
N-Channel 30-V MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)	Q _g (Typ.)			
30	0.0045 at V _{GS} = 10 V	20	24			
	0.006 at V _{GS} = 4.5 V	17	24			

FEATURES

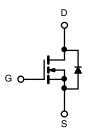
- Halogen-free According to IEC 61249-2-21 Available
- TrenchFET® Power MOSFETs
- 100 % R_g Tested





Ordering Information: Si4430BDY-T1-E3 (Lead (Pb)-free)

Si4430BDY-T1-GE3 (Lead (Pb)-free and Halogen-free)



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	T _A = 25 °C, unle	ss otherwise r	noted		
Parameter		Symbol	10 s	Steady State	Unit
Drain-Source Voltage		V _{DS}	30		.,
Gate-Source Voltage		V _{GS}	± 20		V
Continuous Dunin Comment /T 150 00\0	T _A = 25 °C		20	14	
Continuous Drain Current (T _J = 150 °C) ^a	T _A = 70 °C	· I _D	16	11	
Pulsed Drain Current		I _{DM}	± 60		Α
Continuous Source Current (Diode Conduction) ^a		I _S	2.7	1.40	
Avalanche Current	L = 0.1 mH	I _{AS}		40	
Single Pulse Avalanche Energy	L=0.1 mn	E _{AS}		80	mJ
W	T _A = 25 °C	P _D	3.0	1.6	W
Maximum Power Dissipation ^a	T _A = 70 °C		2.0	1.0	
Operating Junction and Storage Temperature Ra	T _J , T _{stg}	- 55	to 150	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
M :	t ≤ 10 s	R_{thJA}	34	41	°C/W
Maximum Junction-to-Ambient (MOSFET) ^a	Steady State		67	80	
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	15	19	

Notes

a. Surface Mounted on 1" x 1" FR4 board.

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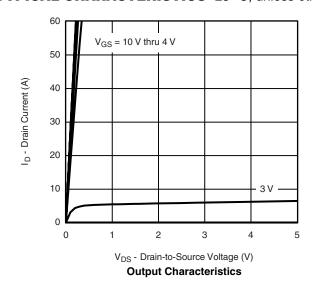
Parameter	Symbol	Test Conditions Mi		Тур.	Max.	Unit	
Static	•						
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$ 1.0			3.0	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zana Cata Valtana Busin Comunit	l	V _{DS} = 30 V, V _{GS} = 0 V			1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V, T _J = 70 °C			10	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	40			Α	
	Ь	V _{GS} = 10 V, I _D = 20 A		0.0037	0.0045	Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 4.5 V, I _D = 17 A		0.0048	0.006		
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 20 A		80		S	
Diode Forward Voltage ^a	V_{SD}	I _S = 2.7 A, V _{GS} = 0 V		0.72	1.1	V	
Dynamic ^b							
Total Gate Charge	Q_g			24	36		
Gate-Source Charge	Q_{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 20 \text{ A}$		10.5		nC	
Gate-Drain Charge	Q_{gd}			7.5			
Gate Resistance	R_g		0.5	1.1	1.7	Ω	
Turn-On Delay Time	t _{d(on)}			20	30		
Rise Time	t _r	V_{DD} = 15 V, R_L = 15 Ω		14	22		
Turn-Off Delay Time	t _{d(off)}	$I_D\cong$ 1 A, V_{GEN} = 10 V, R_g = 6 Ω		60	90	ns	
Fall Time	t _f			18	30		
Course Drain Deverse Beauty Time	t _{rr}	I _E = 2.7 A, dl/dt = 100 A/us		35	50		
Source-Drain Reverse Recovery Time	Q _{rr}	$I_F = 2.7 \text{ A}, \text{ ul/ul} = 100 \text{ A/} \mu\text{S}$		32	50	nC	

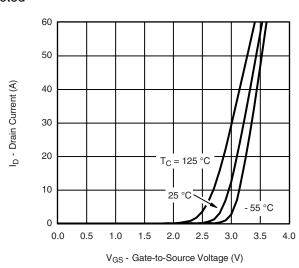
Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



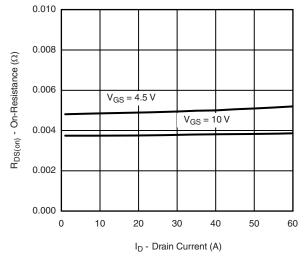


Transfer Characteristics

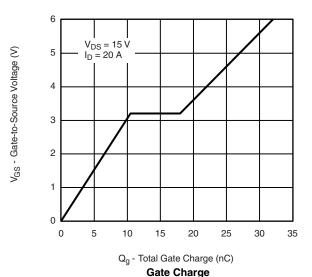


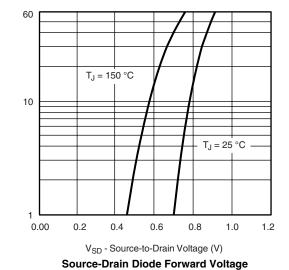


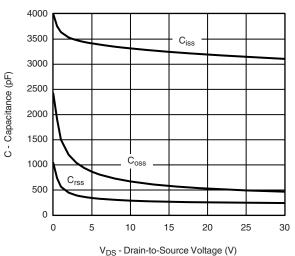
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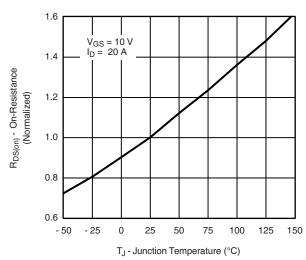
On-Resistance vs. Drain Current



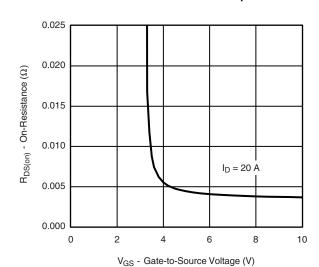




Capacitance



On-Resistance vs. Junction Temperature



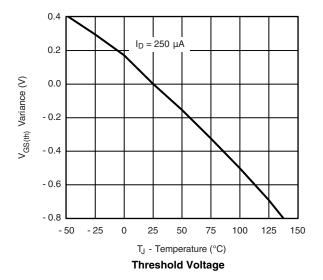
On-Resistance vs. Gate-to-Source Voltage

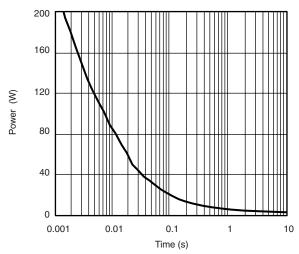
Is - Source Current (A)

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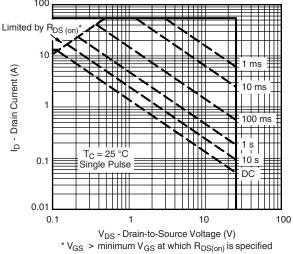
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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

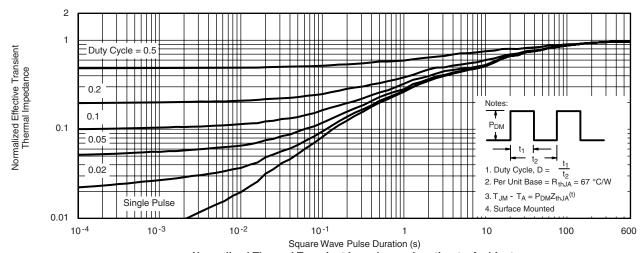




Single Pulse Power



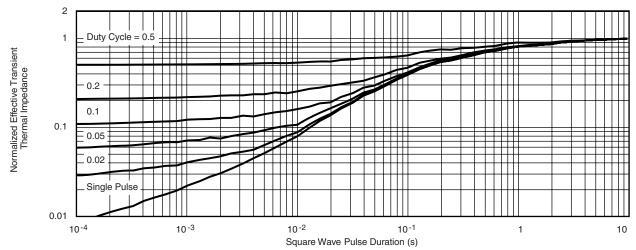
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



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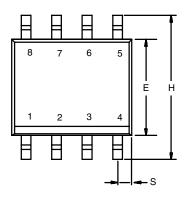


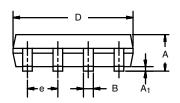
Normalized Thermal Transient Impedance, Junction-to-Foot

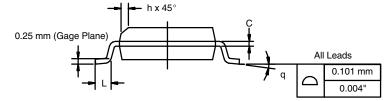
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SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







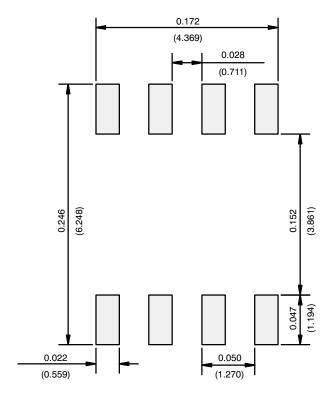
	MILLIM	IETERS	INCHES			
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
Е	3.80	4.00	0.150	0.157		
е	1.27 BSC		0.050	0 BSC		
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C-06527-Rev. I. 11-Sep-06						

DWG: 5498

Document Number: 71192 www.vishay.com 11-Sep-06



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

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